

<b>Position Title:</b>	Package Assembly Operator – Many Shifts			<b>Position # or Level :</b>	QPT OPER
<b>Department:</b>	Manufacturing		<b>Reports to:</b>	Manufacturing Manager	
<b>Employment Status:</b>	Regular Full Time	<b>Pay Grade or salary range:</b>		<b>% Travel Required</b>	NA

**Position Summary:** QP Technologies (formerly Quik-Pak) is a leading provider of microelectronic packaging and assembly, wafer preparation, and substrate design and development services and our service offerings enable our customers to target a range of end markets, including commercial, RF, power, industrial, automotive, medical and mil-aero. As a Package/Assembly Operator, you will work on some of the most advanced hardware technology in the world in an atmosphere that is stimulating, team spirited, and customer focused.

- Essential Duties:**
- Responsible for packaging/assembly of semiconductor devices (training disciplines include Wire Bonding, Silicon Wafer Prep, Silicon Die Attach, Plastic Encapsulation/Lid Seal, Surface Mount, Plastic Package Decapsulation and more).
  - Meet production, quality, and efficiency standards.
  - Work under a microscope for extended periods, at times
  - Read and follow written as well as verbal work instructions

**Minimum Qualifications:** Education, Experience & Citizenship Requirements

- High School diploma or equivalent
- Able to work in a cleanroom environment and follow strict gowning and ESD (ElectroStatic Discharge) protocols.
- Able to use microscopes and various other semiconductor equipment.
- Must have excellent hand dexterity.
- Must be able to read and write English.
- **Must be a US Citizen or legal Permanent Resident.**

- Key Competencies**
- Detail oriented and exhibit a high level of accuracy.
  - Team player that takes pride in their work – yes!!

**Preferred Skills:** Prior experience working on microelectronic devices or working in an ISO certified and/or ITAR registered environment is highly preferred.